

## RoHS2.0 指令附件 III 豁免清单

(适用于所有电子电气设备)

| Exemption<br>豁免 |  | Scope and dates of applicability<br>范围和应用日期   |
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| 1               | Mercury in single capped (compact) fluorescent lamps not exceeding (per burner):<br>单端 (紧凑型) 荧光灯中的汞含量不得超过 (每灯)                               |   |
| 1(a)            | For general lighting purposes < 30 W: 5 mg<br>一般照明用途, 功率 < 30W : 5mg   | Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011 until 31 December 2012; 2,5 mg shall be used per burner after 31 December 2012<br>2011 年 12 月 31 日到期;<br>2011 年 12 月 31 日至 2012 年 12 月 31 日按照 3.5mg/灯;<br>2012 年 12 月 31 日后按照 2.5mg/灯 |
| 1(b)            | For general lighting purposes ≥ 30 W and < 50 W: 5 mg<br>一般照明用途, 功率 ≥ 30W 且 < 50W : 5mg  | Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日到期;<br>2011 年 12 月 31 日至 2012 年 12 月 31 日按照 3.5mg/灯;   |
| 1(c)            | For general lighting purposes ≥ 50 W and < 150 W: 5 mg<br>一般照明用途, 功率 ≥ 50W 且 < 150W : 5mg  |   |
| 1(d)            | For general lighting purposes ≥ 150 W: 15 mg<br>一般照明用途, 功率 ≥ 150W : 15mg   |   |
| 1(e)            | For general lighting purposes with circular or square structural shape and tube diameter ≤ 17 mm<br>一般照明用途, 圆形或方形结构, 管直径 ≤ 17mm              | No limitation of use until 31 December 2011; 7 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制;<br>2011 年 12 月 31 日后 : 7mg/灯   |
| 1(f)            | For special purposes: 5 mg<br>特殊用途 : 5 mg  |   |
| 1(g)            | For general lighting purposes < 30 W with a lifetime equal or above 20 000 h: 3,5 mg<br>一般照明用途, 功率 < 30 W, 寿命 ≥ 20000h : 3.5 mg              | Expires on 31 December 2017<br>2017 年 12 月 31 日   |
| 2(a)            | Mercury in double-capped linear fluorescent lamps for general lighting purposes not exceeding (per lamp):<br>用于一般照明用途的双端直型荧光灯中的汞含量不得超过 (每灯): |   |

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| 2(a)(1) | Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2): 5 mg<br>正常使用寿命下的管直径 < 9mm 的三基色直型荧光灯(例如 T2) 中 : 5mg   | Expires on 31 December 2011; 4 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日到期 ;<br>2011 年 12 月 31 日后 : 4mg/灯                     |
| 2(a)(2) | Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (e.g. T5): 5 mg<br>正常使用寿命下的管直径 ≥ 9mm 且 ≤ 17mm 的基色直型荧光灯 (例如 T5) 中 : 5 mg   | Expires on 31 December 2011; 3 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日到期 ;<br>2011 年 12 月 31 日之后 : 3mg/灯                    |
| 2(a)(3) | Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and ≤ 28 mm (e.g. T8): 5 mg<br>正常使用寿命下的管直径 > 17 mm 且 ≤ 28mm 的基色直型荧光灯 (例如 T8) 中 : 5 mg  | Expires on 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日到期 ;<br>2011 年 12 月 31 日之后 : 3.5mg/灯                |
| 2(a)(4) | Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12): 5 mg<br>正常使用寿命下的管直径 > 28mm 的三基色直型直型荧光灯 (例如 T12) 中 : 5 mg   | Expires on 31 December 2012; 3,5 mg may be used per lamp after 31 December 2012<br>2012 年 12 月 31 日到期 ;<br>2012 年 12 月 31 日之后 : 3.5mg/灯                |
| 2(a)(5) | Tri-band phosphor with long lifetime (≥ 25 000 h): 8 mg<br>长效使用寿命下 (≥ 25000 个 h) 的三基色直型荧光灯 : 8 mg   | Expires on 31 December 2011; 5 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日到期 ;<br>2011 年 12 月 31 日后 : 5mg/灯                     |
| 2(b)    | Mercury in other fluorescent lamps not exceeding (per lamp):<br>其他类型荧光灯中汞含量不得超过   |  |
| 2(b)(1) | Linear halophosphate lamps with tube > 28 mm (e.g. T10 and T12): 10 mg<br>管直径 > 28mm 的线性卤磷酸盐灯 (例如 T10 和 T12) : 10 mg  | Expires on 13 April 2012<br>2012 年 4 月 13 日到期  |
| 2(b)(2) | Non-linear halophosphate lamps (all diameters): 15 mg<br>非线性卤磷酸盐灯 (所有直径) : 15mg   | Expires on 13 April 2016<br>2016 年 4 月 13 日到期  |
| 2(b)(3) | Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9)<br>管直径 > 17mm 的非线性三基色荧光灯 (例如 T9)  | No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 15mg/灯 |
| 2(b)(4) | Lamps for other general lighting and special purposes (e.g. induction lamps)<br>用于其他一般照明用途或特殊照明用途的灯 (例如感应灯)   | No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 15mg/灯 |
| 3       | Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp):<br>特殊用途的冷阴极荧光灯和外置电极荧光灯 (CCFL 和 EEFL) 中的汞含量不得超过 (每灯) |  |

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| 3(a)     | Short length ( $\leq 500$ mm)<br>较短长度 ( $\leq 500$ mm)   | No limitation of use until 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 3.5mg/灯 |
| 3(b)     | Medium length ( $> 500$ mm and $\leq 1\,500$ mm)<br>中等尺寸 ( $>500$ mm 且 $\leq 1500$ mm 之间)  | No limitation of use until 31 December 2011; 5 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 5mg/灯     |
| 3(c)     | Long length ( $> 1\,500$ mm)<br>较长尺寸 ( $>1500$ mm)   | No limitation of use until 31 December 2011; 13 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 13mg/灯   |
| 4(a)     | Mercury in other low pressure discharge lamps (per lamp)<br>其他低压放电灯中汞含量 (每灯)   | No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 15mg/灯   |
| 4(b)     | Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner) in lamps with improved colour rendering index $R_a > 60$ :<br>用于一般照明用途的演色性指数 $R_a > 60$ 高压钠蒸汽灯中汞含量不得超过 |  |
| 4(b)-I   | $P \leq 155$ W<br>功率 $\leq 155$ W  | No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 30mg/灯 |
| 4(b)-II  | $155$ W $< P \leq 405$ W<br>功率 $< 155$ W 且 $\leq 405$ W  | No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 40mg/灯 |
| 4(b)-III | $P > 405$ W<br>功率 $> 405$ W  | No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制 ;<br>2011 年 12 月 31 日后 : 40mg/灯 |
| 4(c)     | Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner):   | 用于一般照明用途的其他高压钠蒸汽灯 (每灯)   |

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| 4(c)-I   | P ≤ 155 W<br>功率 ≤ 155W  | No limitation of use until 31 December 2011; 25 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制；<br>2011 年 12 月 31 日后：25mg/灯 |
| 4(c)-II  | 155 W < P ≤ 405 W<br>功率 < 155W 且 ≤ 405W   | No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制；<br>2011 年 12 月 31 日后：30mg/灯 |
| 4(c)-III | P > 405 W<br>功率 > 405W  | No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011<br>2011 年 12 月 31 日前无限制；<br>2011 年 12 月 31 日后：40mg/灯 |
| 4(d)     | Mercury in High Pressure Mercury (vapour) lamps (HPMV)<br>高压汞蒸汽等 ( HPMV ) 中的汞   | Expires on 13 April 2015<br>2015 年 4 月 13 日到期   |
| 4(e)     | Mercury in metal halide lamps (MH)<br>金卤灯 ( MH ) 中的汞  |   |
| 4(f)     | Mercury in other discharge lamps for special purposes not specifically mentioned in this Annex<br>本附录中未特别提及的其他用途的放电灯中的汞   |   |
| 4(g)     | Mercury in hand crafted luminous discharge tubes used for signs, decorative or architectural and specialist lighting and light-artwork, where the mercury content shall be limited as follows:<br>20 mg per electrode pair + 0,3 mg per tube length in cm, but not more than 80 mg, for outdoor applications and indoor applications exposed to temperatures below 20 °C;<br>15 mg per electrode pair + 0,24 mg per tube length in cm, but not more than 80 mg, for all other indoor applications.<br>用于标牌、装饰或建筑和专业照明和灯光艺术品中手工制作的发光放电管 ( HDLTs ) 中的汞：<br>每对电极 20mg+0.3mg*灯管长度 ( 单位为 cm ) , 但至多不超过 80mg , 适用于置于温度低于 20°C 的户外和室内应用；<br>每对电极 25mg+0.24mg*灯管长度 ( 单位为 cm ) , 但至多不超过 80mg , 适用于所有其他室内应用 | Expires on 31 December 2018<br>2018 年 12 月 31 日到期   |
| 5(a)     | Lead in glass of cathode ray tubes<br>阴极射线管玻璃中的铅  |   |
| 5(b)     | Lead in glass of fluorescent tubes not exceeding 0,2 % by weight<br>荧光管玻璃中的铅含量不得超过其重量的 0.2%   |   |

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| 6(a)     | Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight<br>机械加工用钢和镀锌钢中合金元素中的铅含量最高可达 0.35%  |  |
| 6(b)     | Lead as an alloying element in aluminium containing up to 0,4 % lead by weight<br>铅用于铝合金，并为其元素之一，含量最高可达 0.4%  |  |
| 6(c)     | Copper alloy containing up to 4 % lead by weight<br>铜中合金元素的铅含量小于 4%   |  |
| 7(a)     | Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)<br>高熔化温度型焊料中的铅（即铅含量超过 85%的铅基合金焊料）   |  |
| 7(b)     | Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for telecommunications<br>用于服务器、存储器和存储阵列系统的焊料中的铅；用于交换、信号和传输及电信网络基础设施中焊料中的铅     |  |
| 7(c)-I   | Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound<br>电子电气元件中玻璃或陶瓷材料（电容中陶瓷介质除外）所含的铅，如压电设备或玻璃/陶瓷复合元件 |  |
| 7(c)-II  | Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher<br>额定电压 125V AC 或 250V DC 或更高的电容器中陶瓷介质所含的铅   |  |
| 7(c)-III | Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC<br>额定电压低于 125V AC 或 250V DC 及以下的电容器中陶瓷介质所含的铅   | Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013<br>2013 年 1 月 1 日到期，之后仅可用作 2013 年 1 月 1 日前投放市场的电子电气产品的备用部件 |
| 7(c)-IV  | Lead in PZT based dielectric ceramic materials for capacitors which are part of integrated circuits or discrete semiconductors<br>集成电路或离散式半导体中的电容器，其锆钛酸铅（PZT）介电陶瓷中的铅  | Expires on 21 July 2016<br>2016 年 7 月 21 日到期   |
| 8(a)     | Cadmium and its compounds in one shot pellet type thermal cut-offs<br>热熔断体中的镉及其化合物  | Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012<br>2012 年 1 月 1 日到期，之后仅可用作 2012 年                          |

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|       |   | 1月1日前投放市场的电子电气产品的备用部件  |
| 8(b)  | Cadmium and its compounds in electrical contacts<br>电触点中的镉及其化合物   |  |
| 9     | Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0,75 % by weight in the cooling solution<br>吸收式电冰箱中作为碳钢冷却系统防腐剂的六价铬，其在冷却液中的含量不得超过 0.75%   |  |
| 9(b)  | Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications<br>暖通空调 (HVACR) 设备压缩机轴承外壳及轴衬中的铅  |  |
| 11(a) | Lead used in C-press compliant pin connector systems<br>C-press 插脚式连接器系统中使用的铅   | May be used in spare parts for EEE placed on the market before 24 September 2010<br>仅可用作 2010 年 9 月 24 日前投放市场的电子电气产品的备用部件  |
| 11(b) | Lead used in other than C-press compliant pin connector systems<br>除 C-press 以外的插脚式连接器系统中使用的铅   | Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013<br>2013 年 1 月 1 日到期，之后仅可用作 2013 年 1 月 1 日前投放市场的电子电气产品的备用部件 |
| 12    | Lead as a coating material for the thermal conduction module C-ring<br>热倒模组 C 环涂层中的铅  | May be used in spare parts for EEE placed on the market before 24 September 2010<br>仅可用作 2010 年 9 月 24 日前投放市场的电子电气产品的备用部件  |
| 13(a) | Lead in white glasses used for optical applications<br>光学玻璃中的铅  |  |
| 13(b) | Cadmium and lead in filter glasses and glasses used for reflectance standards<br>滤光玻璃及反射率标准玻璃片中的铅和镉   |  |
| 14    | Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight<br>微处理器引脚及封装连接所使用的含两种以上组分焊料中的铅 ( 铅含量在 80%到 85%之间 ) | Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011<br>2011 年 1 月 1 日到期，之后仅可用作 2011 年 1 月 1 日前投放市场的电子电气产品的备用部件 |
| 15    | Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages<br>集成电路倒装芯片封装中半导体芯片及载体之间形成可靠联接所用焊料中的铅   |  |

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| 16    | Lead in linear incandescent lamps with silicate coated tubes<br>线性白炽灯硅酸盐灯管中的铅  | Expires on 1 September 2013<br>2013 年 9 月 1 日到期   |
| 17    | Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications<br>用于专业复印设备的高强度放电灯 ( HID ) 中用作激发的卤素铅   |   |
| 18(a) | Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as speciality lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb)<br>用于重氮复印、平版印刷、捕虫器、光化学和食物加工过程的特种放电灯中含磷荧光粉触媒( 如 SMS(Sr, Ba)2Mg2Si2O7:Pb ) 中的铅, 其含量在 1%以下 | Expires on 1 January 2011<br>2011 年 1 月 1 日到期   |
| 18(b) | Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb)<br>仿日晒放电灯中含磷荧光粉触媒( 如 BSP(BaSi2O5:Pb) ) 中的铅, 其含量在 1%以下   |   |
| 19    | Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL)<br>紧凑型节能灯 ( ESL ) 中作为主要汞齐合金的特定成分 ( PbBiSn-Hg 和 PbInSg-Hg ) 中的铅及作为辅助汞合金 PbSn-Hg 中的铅  | Expires on 1 June 2011<br>2011 年 6 月 1 日到期  |
| 20    | Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs)<br>液晶显示器 ( LCD ) 用于连接平面荧光灯前后基片用的玻璃中的氧化铅   | Expires on 1 June 2011<br>2011 年 6 月 1 日到期  |
| 21    | Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses<br>用于玻璃 ( 如硼硅玻璃及钠钙玻璃 ) 瓷釉上印刷油墨的铅和镉   |   |
| 23    | Lead in finishes of fine pitch components other than connectors with a pitch of 0,65 mm and less<br>细间距元器件( 即不大于 0.65mm 的引脚间距 ) 的表面处理的铅, 不包括连接器类。  | May be used in spare parts for EEE placed on the market before 24 September 2010<br>仅可用作 2010 年 9 月 24 日前投放市场的电子电气产品的备用部件 |
| 24    | Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors<br>通孔盘状和平面阵列的多层陶瓷电容中焊料的铅   |   |
| 25    | Lead oxide in surface conduction electron emitter displays   |   |

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|    | (SED) used in structural elements, notably in the seal frit and frit ring<br>表面传导式电子发射显示器( SED )构件所用的氧化铅,特别是密封玻璃和玻璃环  |  |
| 26 | Lead oxide in the glass envelope of black light blue lamps<br>紫光灯/黑光灯(或称蓝黑灯)玻璃壳中的氧化铅  | Expires on 1 June 2011<br>2011年6月1日到期        |
| 27 | Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers<br>在大功率扬声器(针对声功率等级在125dB SPL或更高时运行几小时)中作为转换器焊料的铝合金   | Expired on 24 September 2010<br>2010年9月24日到期 |
| 29 | Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC <a href="#">(1)</a><br>69/493/EEC 指令附录 I (1,2,3 和 4 类) 中限定的水晶玻璃中的铅。<br>(注: 1类 PbO≥30%; 2类 PbO≥24%; 3类 ZnO BaO PbO K2O 单个或总和≥10%; 4类 BaO PbO K2O 单个或总和≥10%) |  |
| 30 | Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more<br>用于位于音量≥100 dB (A)的大功率扩音器音圈上的电导体的电气或机械焊点的镉合金     |  |
| 31 | Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting)<br>用于无汞平面荧光灯(例如:用于液晶显示器、设计或工业照明)的焊料中的铅  |  |
| 32 | Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes<br>用于氩和氪激光管防护窗组合件的封装玻璃材料中的铅化合物  |  |
| 33 | Lead in solders for the soldering of thin copper wires of 100 μm diameter and less in power transformers<br>电源变压器中直径100μm及以下细铜线所用焊料中的铅  |  |
| 34 | Lead in cermet-based trimmer potentiometer elements<br>金属陶瓷微调电位计中的铅   |  |
| 36 | Mercury used as a cathode sputtering inhibitor in DC plasma displays with a content up to 30 mg per display<br>直流等离子显示器中阴极溅射抑制剂中的汞,其含量每台显示器不超过30mg  | Expired on 1 July 2010<br>2010年7月1日过期        |
| 37 | Lead in the plating layer of high voltage diodes on the basis   |  |



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|    | of a zinc borate glass body<br>基于硼酸锌玻璃体的高压二极管的电镀层中的铅   |   |
| 38 | Cadmium and cadmium oxide in thick film pastes used on aluminium bonded beryllium oxide<br>铝结合氧化铍的厚膜浆料中的镉和氧化镉  |   |
| 39 | Cadmium in colour converting II-VI LEDs (< 10 µg Cd per mm <sup>2</sup> of light-emitting area) for use in solid state illumination or display systems<br>应用于固态照明或显示系统中的色彩转换 II-VI 族 LED( 镉含量低于 10µg/mm <sup>2</sup> 发光区域中使用的镉   | Expires on 1 July 2014<br>2014 年 7 月 1 日到期        |
| 40 | Cadmium in photoresistors for analogue optocouplers applied in professional audio equipment<br>用于专业音频设备的模拟光耦合器中使用的光敏电阻中的镉  | Expires on 31 December 2013<br>2013 年 12 月 31 日到期 |
| 41 | Lead in solders and termination finishes of electrical and electronic components and finishes of printed circuit boards used in ignition modules and other electrical and electronic engine control systems, which for technical reasons must be mounted directly on or in the crankcase or cylinder of hand-held combustion engines (classes SH:1, SH:2, SH:3 of Directive 97/68/EC of the European Parliament and of the Council(*))<br>用于点火模块和其他电子电气发动机控制系统中的电子电气元件的焊料和最终表面材料以及用于印刷电路板表面材料中的铅 | Expires on 31 December 2018<br>2018 年 12 月 31 日到期 |

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